

#### **Features**

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low R<sub>DS(ON)</sub>

#### **Product Summary**

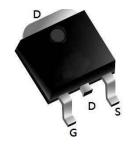


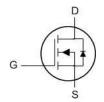
BVDSS	RDSON	ID
100V	8.5mΩ	70A

#### **Applications**

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

#### **TO252-3L Pin Configuration**





**Absolute Maximum Ratings:** 

Symbol	Parameter	Value	Units	
$V_{\mathrm{DSS}}$	Drain-to-Source Voltage	100	V	
T_	Continuous Drain Current $T_C = 25$ °C		70	A
$I_D$	Continuous Drain Current $T_C = 100  ^{\circ}C$		45	A
$I_{DM}^{a1}$	Pulsed Drain Current	280	A	
$E_{AS}^{a2}$	Single pulse avalanche energy	110	mJ	
$V_{GS}$	Gate-to-Source Voltage	±20	V	
$P_D$	Power Dissipation	100	W	
$T_{J}$ , $T_{STG}$	Operating Junction and Storage Range	150, -55 to 150	°C	
$T_{\rm L}$	Maximum Temperature for Soldering		260	°C

#### **Thermal Characteristics:**

Symbol	Parameter	Value	Units
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	1.25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	64	°C/W



## Electrical Characteristics (TA= 25°C unless otherwise specified):

Static Ch	Static Characteristics							
Symbol	Parameter	T C 11.11	Value			Units		
Syllibol	Parameter	Test Conditions	Min.	Typ.	Max.	Ullits		
$V_{\mathrm{DSS}}$	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_{D}=250\mu A$	100			V		
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS}=100V, V_{GS}=0V$			1	μΑ		
I <sub>GSS(F)</sub>	Gate to Source Forward Leakage	$V_{GS} = +20V, V_{DS} = 0V$			100	nA		
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}$ =-20V, $V_{DS}$ =0V			-100	nA		
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{D}=250 \mu A$	1.3	1.8	2.3	V		
Prayer	Drain-to-Source On-	$V_{GS}=10V, I_{D}=20A$		8.5	10.5	m $\Omega$		
$R_{\rm DS(ON)}$	Resistance	$V_{GS}$ =4.5V, $I_{D}$ =15A		9.5	15	m $\Omega$		

Dynamic	Dynamic Characteristics							
Symbol	Parameter	Test Conditions	Value			Units		
Syllibol	rarameter	Test Conditions	Min.	Typ.	Max.	Units		
$C_{iss}$	Input Capacitance	V = 0V	1	1368	1			
$C_{oss}$	Output Capacitance	$V_{GS} = 0V$ $V_{DS} = 50V$		451		рF		
C <sub>rss</sub>	Reverse Transfer Capacitance	$V_{DS} = 50V$ $f = 1.0MHz$		12.9		pr		
$R_g$	Gate resistance	V <sub>GS</sub> =0V,V <sub>DS</sub> Open		0.48		Ω		

Resistive	Switching Characteristics					
Crym h a l	D	Test Conditions	Value			Units
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Ullits
t <sub>d(ON)</sub>	Turn-on Delay Time	$I_D = 10A$		16		
tr	Rise Time	$V_{DS} = 50V$		10		
$t_{d(OFF)}$	Turn-Off Delay Time	$V_{GS} = 10V$		40		ns
$t_{\mathrm{f}}$	Fall Time	$R_G = 4\Omega$		6		
Qg	Total Gate Charge	$V_{GS} = 10V$		31.3		
$Q_{gs}$	Gate Source Charge	$V_{DS} = 50V$		3.49		nC
Q <sub>gd</sub>	Gate Drain Charge	$I_D = 10A$		7.63		

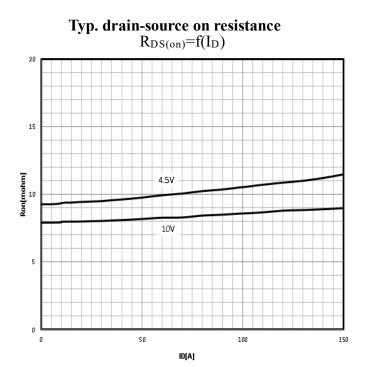
Source-Drain Diode Characteristics								
Cyron la o 1	Danamatan	T. (C. 1'('	Value			Value		
Symbol Parameter		Test Conditions	Min.	Тур.	Max.	value		
$I_S$	Diode Forward Current	T <sub>C</sub> =25 °C			70	A		
$V_{SD}$	Diode Forward Voltage	$I_S=10A, V_{GS}=0V$			1.2	V		
$t_{rr}$	Reverse Recovery time	$I_{S}=10A, V_{DD}=50V$		103		ns		
Q <sub>rr</sub>	Reverse Recovery Charge	$dI/dt=100A/\mu s$		187		nC		

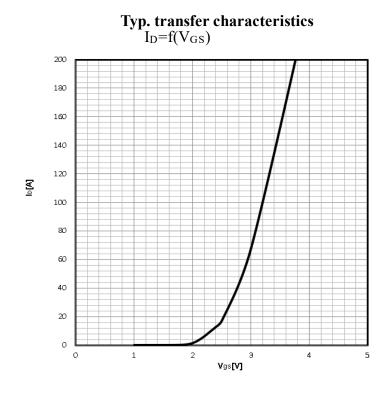
 $<sup>^{</sup>a1}$ : Repetitive rating; pulse width limited by maximum junction temperature  $^{a2}$ : VDD=50V, L=0.3mH, Rg=25 $\Omega$ , Starting TJ=25  $^{\circ}C$ 

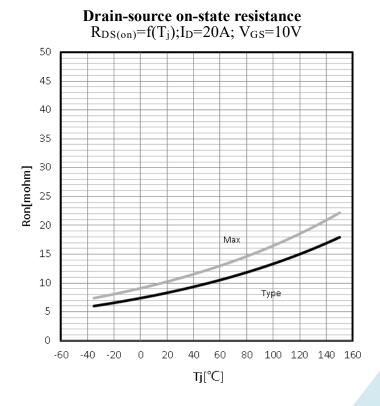


#### **Characteristics Curve:**

Typ. output characteristics  $I_D = f(V_{DS})$ 

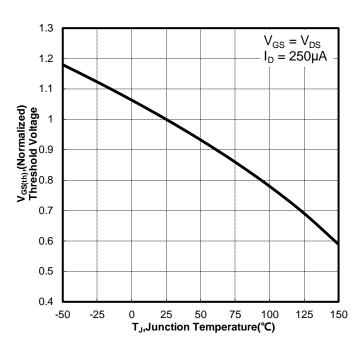




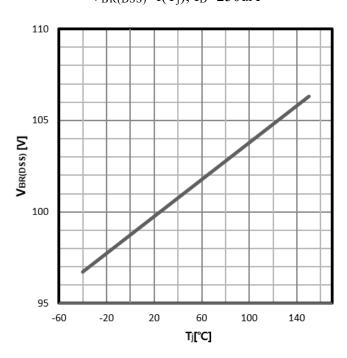




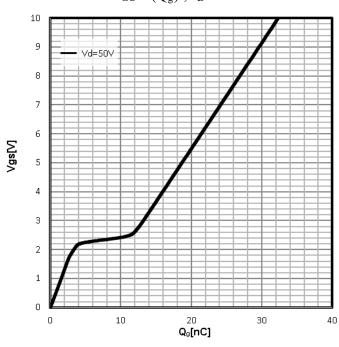
Gate Threshold Voltage  $V_{TH}=f(T_j); I_D=250uA$ 



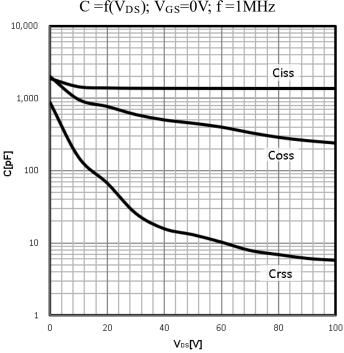
Drain-source breakdown voltage  $V_{BR(DSS)}=f(T_i)$ ;  $I_D=250uA$ 



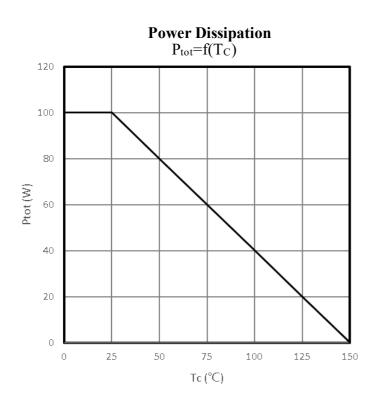
Typ. gate charge  $V_{GS}$ = $f(Q_g)$ ;  $I_D$ =10A

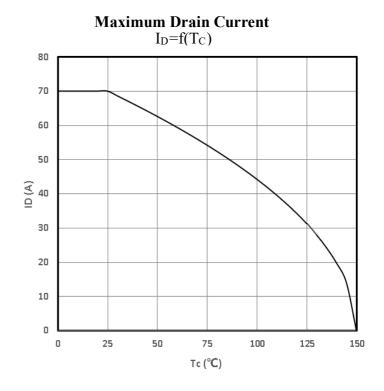


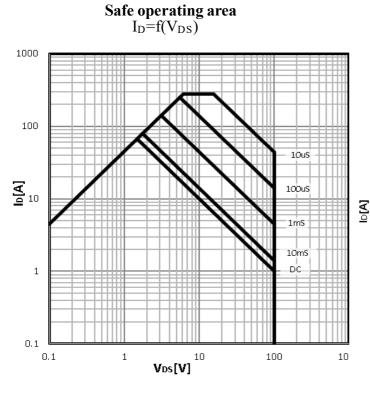
Typ. capacitances  $C = f(V_{DS}); V_{GS} = 0V; f = 1MHz$ 

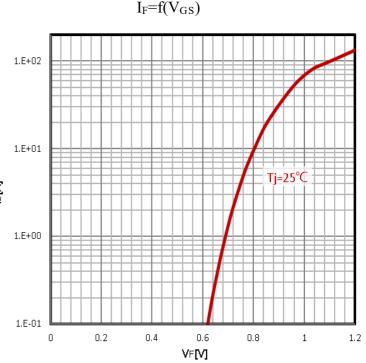










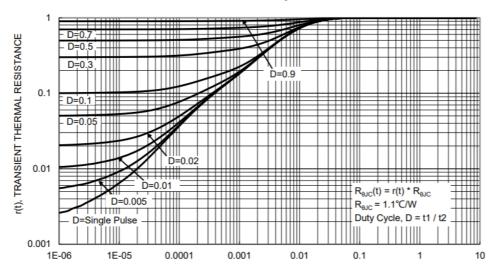


**Body Diode Forward Voltage Variation** 



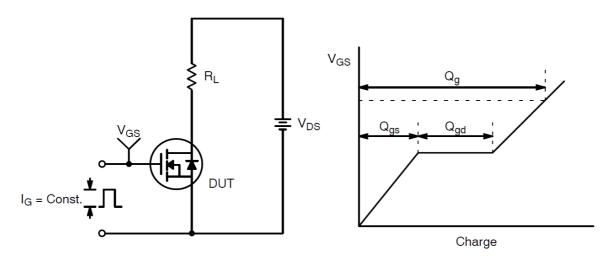
# Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$

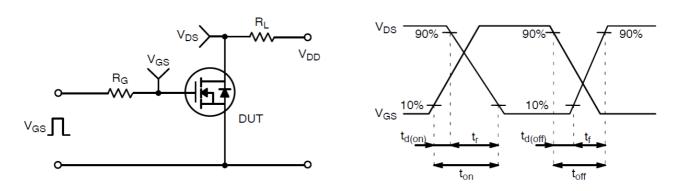




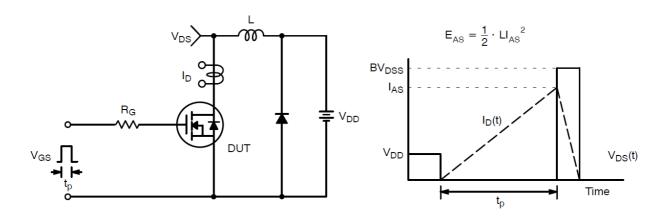
#### **Test Circuit and Waveform:**



**Gate Charge Test Circuit & Waveform** 



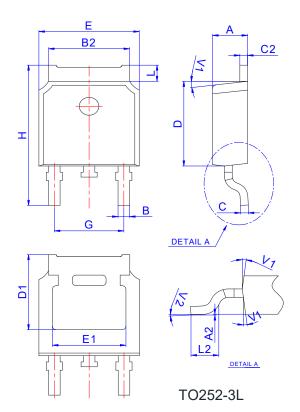
**Resistive Switching Test Circuit & Waveforms** 



**Unclamped Inductive Switching Test Circuit & Waveforms** 

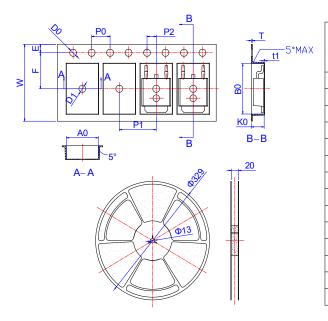


# Package Mechanical Data-TO252-3L



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			(	).209REF	=
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

# Reel Spectification-TO252-3L



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
Т	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583